

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.75096	100.0	25
			<b>Subtotal</b>	<b>1.75096</b>	<b>100</b>	<b>25</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.42751	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.30346	16.0	90
	Filler	Silica fused	60676-86-0	29.54749	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11819	0.3	1.6875
			<b>Subtotal</b>	<b>39.39665</b>	<b>100</b>	<b>562.5</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02328	0.04	0.3324
	Copper alloy	Iron (Fe)	7439-89-6	0.0582	0.1	0.831
	Copper alloy	Copper (Cu)	7440-50-8	58.1205	99.86	829.8366
			<b>Subtotal</b>	<b>58.20198</b>	<b>100</b>	<b>831</b>
Die		Lead Dioxide (PbO2)	1309-60-0	0.00251	1.06	0.03586
		Silicon (Si)	7440-21-3	0.23444	98.94	3.3473
			<b>Subtotal</b>	<b>0.23695</b>	<b>100</b>	<b>3.38316</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.22412	100.0	3.2
			<b>Subtotal</b>	<b>0.22412</b>	<b>100</b>	<b>3.2</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.00947	5.0	0.13516
	Lead alloy	Silver (Ag)	7440-22-4	0.00473	2.5	0.06758
	Lead alloy	Lead (Pb)	7439-92-1	0.17512	92.5	2.5004
			<b>Subtotal</b>	<b>0.18932</b>	<b>100</b>	<b>2.70314</b>
			<b>Total</b>	<b>99.99998</b>	<b>100</b>	<b>1427.7863</b>

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